## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

pplication Serial No. ......10/734,419 Filing Date...... December 11, 2003 Inventor......John T. Moore et al. Assignee ...... Micron Technology, Inc. Examiner ...... Warren, Matthew E. Attorney's Docket No. ......MI22-2463 Title: Semiconductor Wafer Assemblies Comprising Photoresist Over Silicon Nitride Materials

## SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

To:

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

From:

Jennifer J. Taylor, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)

Wells St. John P.S.

601 W. First Avenue, Suite 1300

Spokane, WA 99201-3828

Dear Sir:

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449.

Citation of these references is respectfully requested.

A check in the amount of \$180.00 is enclosed to cover the fee specified under 37 C.F.R. § 1.17(p).

Respectfully submitted,

Dated: 11/a/19, 2005

By:

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Form PTO-1449

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

MAY 1 9 2005 LIST OF ART CITED BY APPLICA (Use several sheets if necessary)

ATTY. DOCKET NO. M122-2463

SERIAL NO. 10/734,419

APPLICANT John T. Moore et al.

FILING DATE December 11, 2003 GROUP 2815

## U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Subclass	Fili If Ap	ng Date propriate
	AA	6,756,634	06-2004	Helm et al.				
	AB							
	AC	-						
	AD							
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.